Snap attachment adhesive (World's shortest tact time)

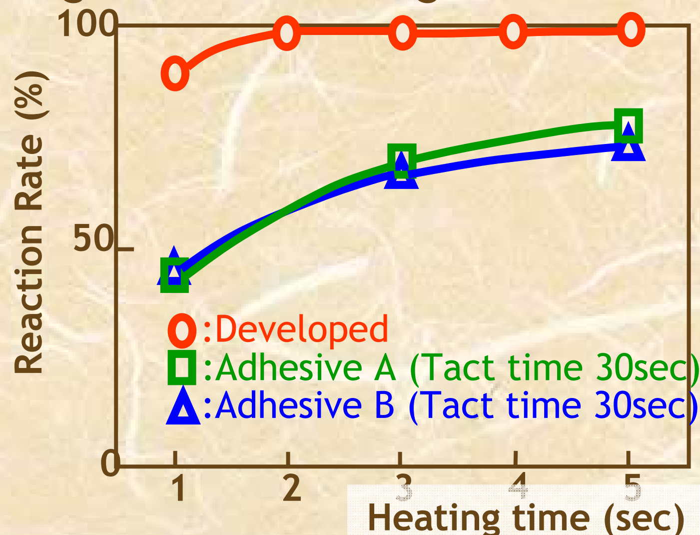
Batch reflow for Au bump: Hardening need to complete on the FC bonder

Reduction of the hardening time is essential for Low cost / High capability

Material

Design accelerator with rapid reaction speed

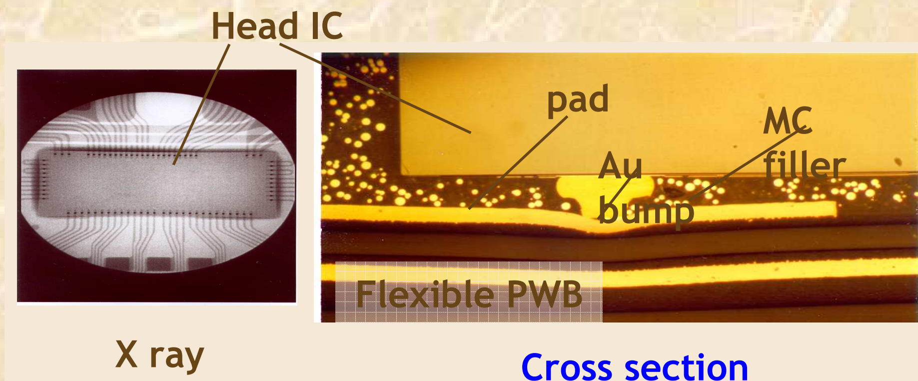
Elevate the internal temp of the Adhesive through the self-heating



Less cure time : 30 sec ➡ 3 sec

Contact reliability

Curing conditions: 195 degC, 3 sec, 20g/bump



TCT: -65 deg C - 125degC, 1000 cycles
Damp-heat biased: 85degC, 85RH%, DC5V, 1000h
High temperature storage: 150degC, 1000h

Satisfy the reliability requirements

For HDD head amplifier IC, CMOS chip for camera in mobile phone

伊達仁昭　他、「ベアチップ実装用短タクト型異方導電性接着剤」、第15回エレクトロニクス実装学会学術講演大会論文集、pp125-126